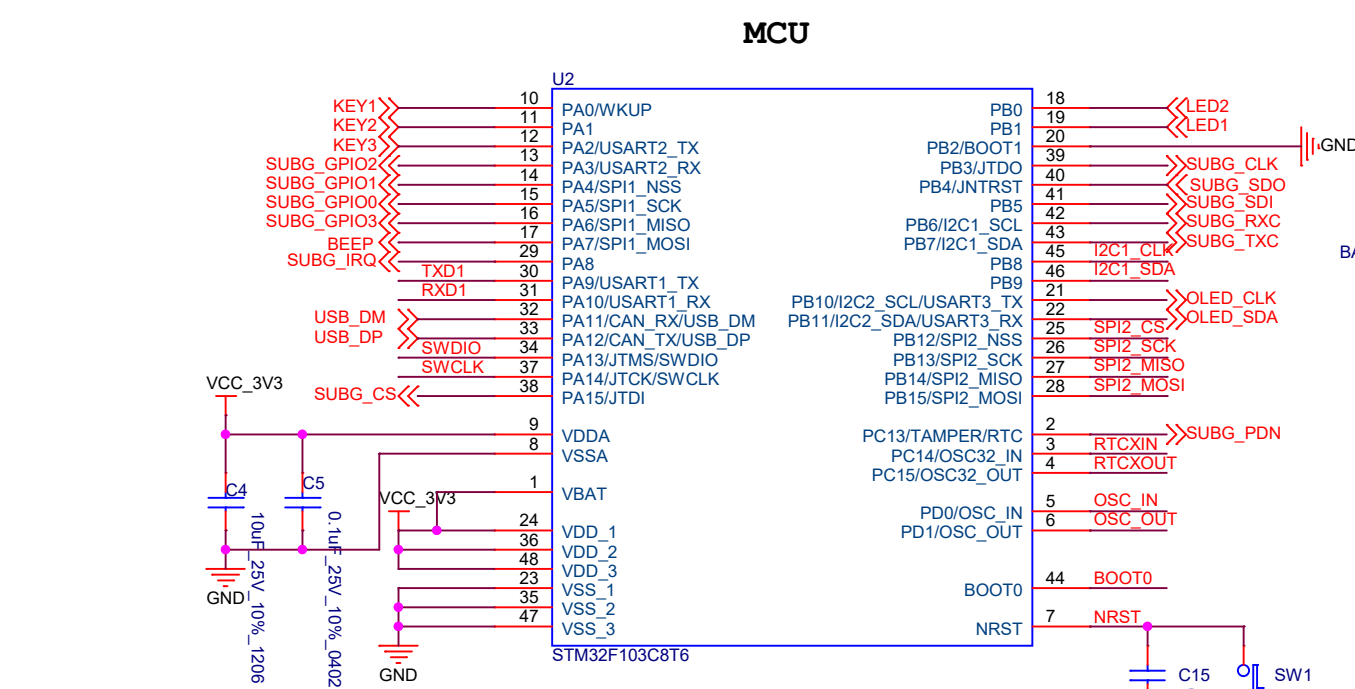
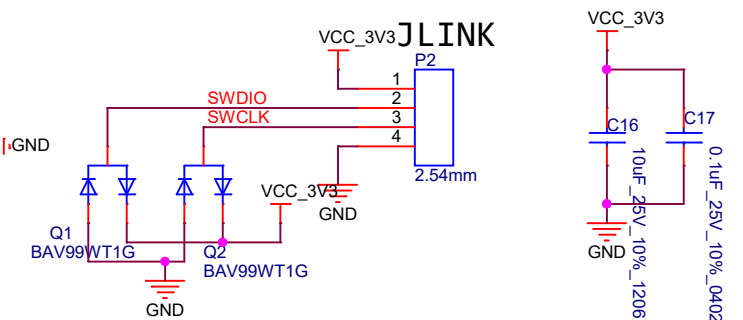


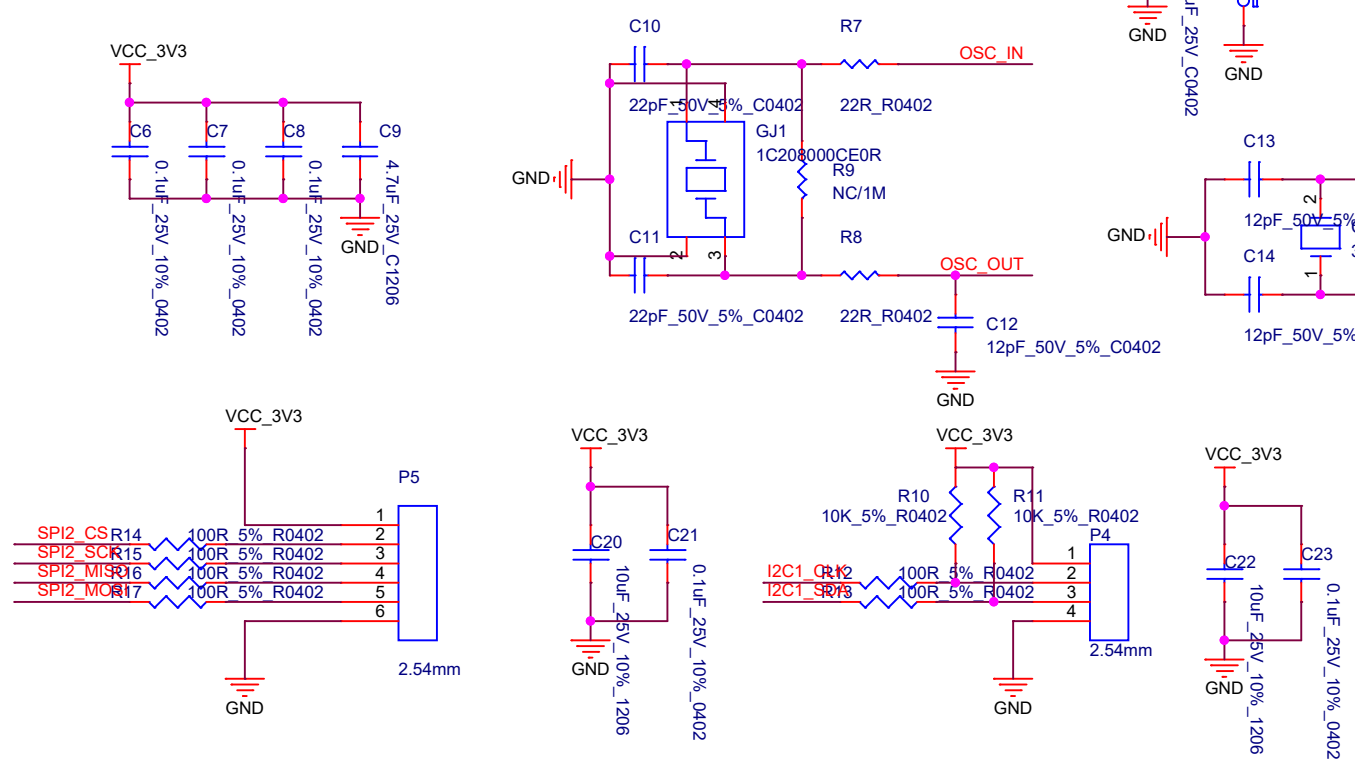
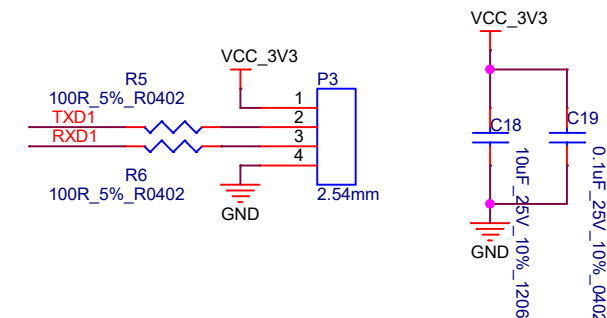
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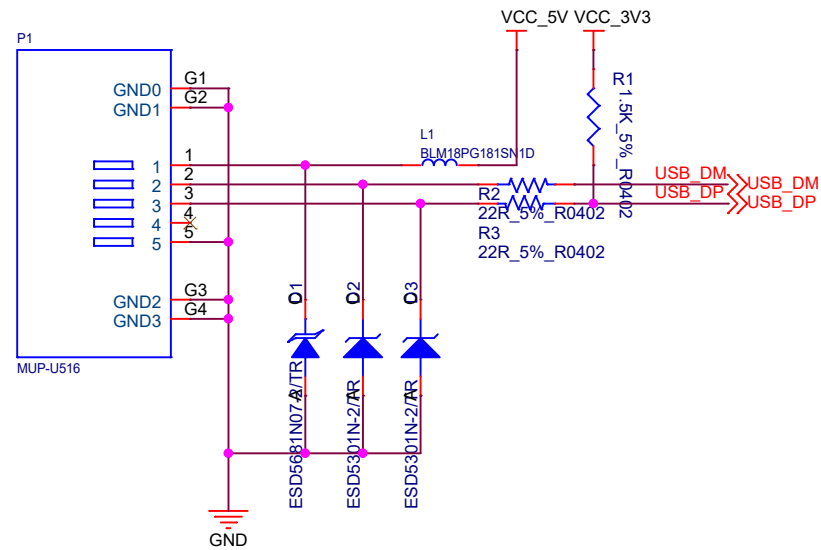
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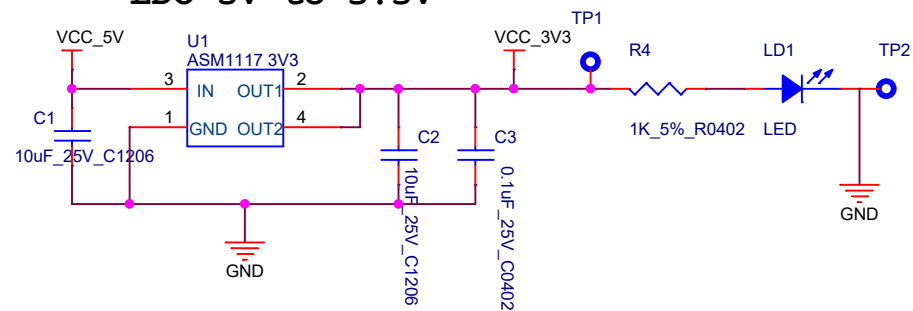
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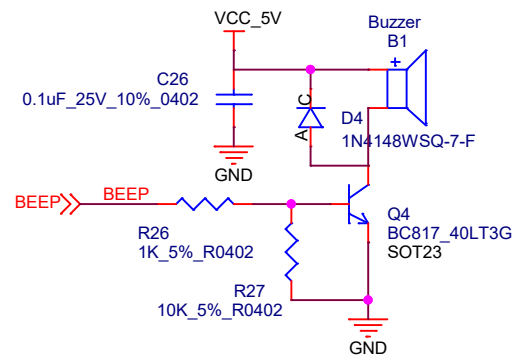
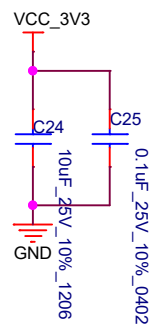
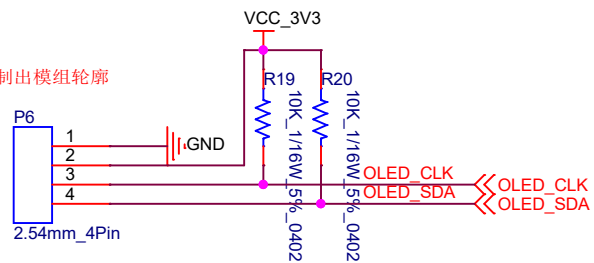


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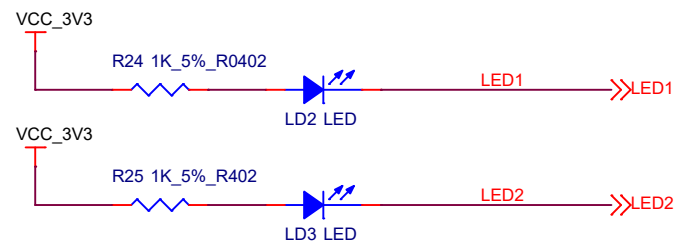
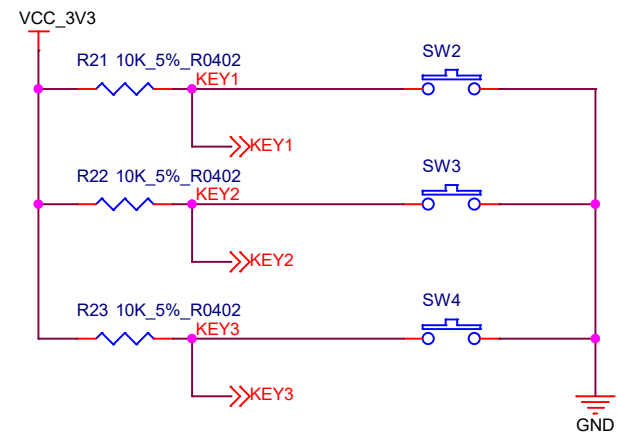


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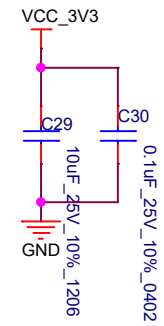
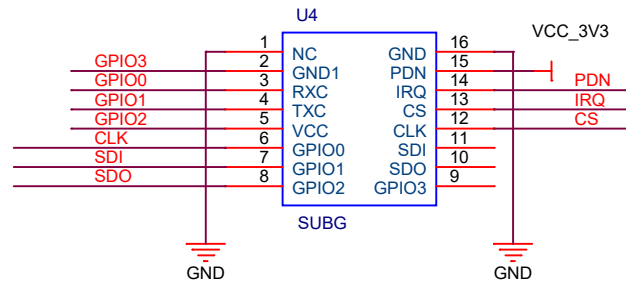
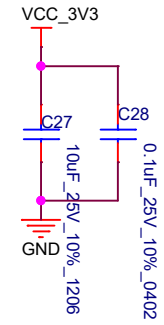
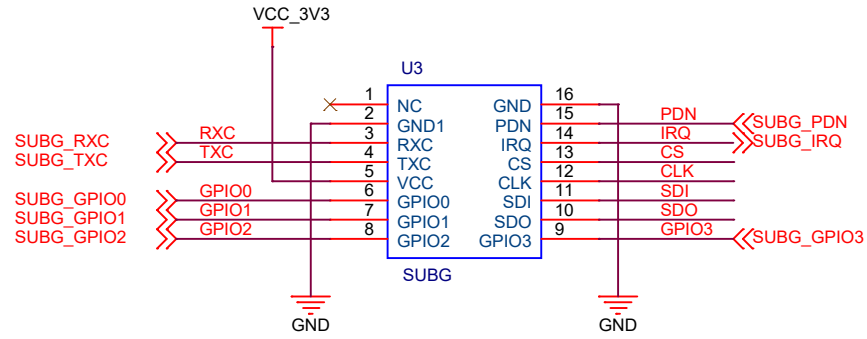
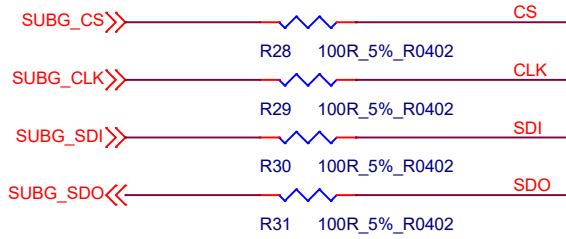
需要再板上绘制出模组轮廓



KeyLed



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Date:	Monday, June 01, 2020		Sheet 1 of 1



按照新模块修改引脚顺序

2.0mm双排通孔焊盘，距离按照SUBG模块尺寸放置